



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of: **MIYAJIMA, Takashi et al.**

Serial No.: **09/996,736**

Filed: **November 30, 2001**

Group Art Unit: **2827**

Examiner: **DINH, TUAN T.**

P.T.O. Confirmation No.: 4486

For. **PRINTED WIRING BOARD UNIT, AUXILIARY SUBSTRATE FOR
HIERARCHICAL MOUNTING, AND ELECTRONIC APPARATUS**

RESPONSE UNDER 37 CFR §1.111

Commissioner for Patents
Washington, D.C. 20231

November 20, 2002

Sir:

In response to the Office Action dated **August 29, 2002**, please consider the following remarks in connection therewith.

REMARKS

Claims 1-12 are pending in the application.

Claim Rejections under 35 USC §103

Claims 1, 7 and 11-12 are rejected under 35 USC §103(a) as being unpatentable over Kledzik et al. (U.S. Patent No. 6,313,998) in view of Hernandez et al. (cited by Applicant).

It should be noted that the printing wiring board pads 36a of the auxiliary substrate for hierarchical mounting 14 of the present invention are formed on the lower surface 14f of the auxiliary substrate 14.

In contradistinction, the carrier leads 109 extend from the side of the carrier 105

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Response
J. J. Smith
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